

PREFACE

Message from the DOLAP 2019 Chairs

The International Workshop On Design, Optimization, Languages and Analytical Processing of Big Data is continuing its unbreakable service for 21 years. Until 2015 the workshop was known as the International Workshop on Data Warehousing and OLAP (DOLAP). To keep the link with the past, we are still using the DOLAP acronym.

Previous DOLAP workshops were held in Bethesda, Maryland, USA (1998), Kansas City, Missouri, USA (1999), Washington, DC, USA (2000), Atlanta, Georgia, USA (2001), McLean, Virginia, USA (2002), New Orleans, LA, USA (2003), Washington, DC, USA (2004), Bremen, Germany (2005), Arlington, Virginia, USA (2006), Lisbon, Portugal (2007), Napa Valley, California, USA (2008), Hong Kong, China (2009), Toronto, Ontario, Canada (2010), Glasgow, United Kingdom (2011), Maui, HI, USA (2012), San Francisco, CA, USA (2013), Shanghai, China (2014), Melbourne, VIC, Australia (2015), Venice, Italy (2017), Vienna, Austria (2018). DOLAP editions since 1998 until 2015 were associated with the CIKM conference, and the proceedings were published by ACM. Since 2017, DOLAP is associated with the EDBT/ICDT conference, having its proceedings open-access, made available on-line by <http://ceur-ws.org/>

Over 20 years of history, makes DOLAP one of the most recognized and appreciated events worldwide focusing on data warehousing technologies and on broad range of data analytics techniques, for both standard and big data.

We observe that papers being submitted to DOLAP within 21 years, have addressed 28 different groups of topics, among them the most popular include: (1) modeling and design, (2) ETL, data profiling and cleaning, (3) business intelligence and data analytics, (4) data integration architectures, techniques, and algorithms, (5) database/warehouse architectures, (6) query processing and optimization, (7) NoSQL technologies.

For DOLAP 2019 we received 26 submissions. This year, similarly as in the 2018 DOLAP edition, we applied a 2-phase reviewing process, for the purpose of improving the quality of papers, bot in terms of research contributions and clarity of presentations. As the result of this process, 12 papers were accepted for the workshop - 7 regular and 5 short, resulting in a total acceptance rate of 46%. The papers cover the following topics: business intelligence and data analytics, data pre-processing, indexing, optimization of analytical processing, data warehouse modeling and designing. On top of that, DOLAP 2019 hosted two invited talks: (1) 'ETL in Big Data Architectures: IBM Approach to Design and Optimization of ETL Workflows', by Michal Bodziony (IBM Poland) and (2) 'Automating Data Preparation: Can We? Should We? Must We?', by Norman Paton (University of Manchester, UK).

The DOLAP 2019 Chairs would like to thank the Program Committee Members for their thorough and timely work. This year (again), 100% of reviews were delivered on time!

February 2019

DOLAP 2019 General Chair
Il-Yeol Song
DOLAP 2019 Program Chairs
Oscar Romero
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